

## 9-LINE LVD-ONLY SCSI TERMINATOR WITH INTEGRATED SPI-3 DELAYS AND REVERSE DISCONNECT

SLUS441A - MARCH 1999 - REVISED AUGUST 2000

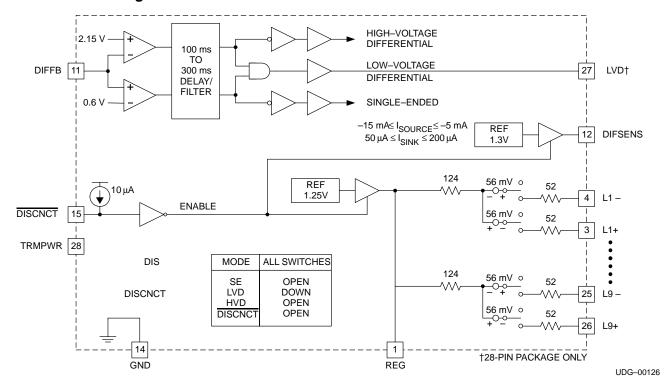
- LVD-Only Active Termination
- 2.7 V to 5.25 V Operation
- Differential Failsafe Bias
- Built-In SPI-3 Mode Change Filter/Delay
- Standards Supported: SPI-3, Ultra2 (Fast 40), Ultra3/Ultra160 (Fast 80)
- Reversed Disconnect Polarity

### description

The UCC5681 is an LVD-only Small Computer System Interface (SCSI) terminator that integrates the mode change delay function required by the SPI-3 specification. The device senses what types of SCSI drivers are present on the bus via the voltage on the DIFFSENS SCSI control line. Single-ended (SE) and high-voltage differential (HVD) SCSI drivers (EIA485) are not supported. If the chip detects the presence of an SE or HVD SCSI driver, it disconnects itself by switching all terminating resistors off the bus and enters a high-impedance state. The terminator can also be commanded to disconnect the terminating resistors with the DISCNCT input. Impedance is trimmed for accuracy and maximum effectiveness. Bus lines are biased to a failsafe state to ensure signal integrity.

The UCC5681 is offered in both 24-pin and 28-pin TSSOP (PW) packages for a temperature range of 0°C to 70°C.

### functional block diagram





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## UCC5681 9-LINE LVD-ONLY SCSI TERMINATOR WITH INTEGRATED SPI-3 DELAYS AND REVERSE DISCONNECT

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	24-PIN PW PACKAGE (TOP VIEW)		2	8-PIN PW PACKAGE (TOP VIEW)	
REG 1 L1+ 2 L1- 3 L2+ 4 L2- 5 L3+ 6 L3- 7	0	24 TRMPWR 23 L9+ 22 L9 - 21 L8+ 20 L8 - 19 L7+ 18 L7 -	REG 1 C N/C 2 L1+ 3 L1 - 4 L2+ 5 L2 - 6 L3+ 7 L3 - 8		28 TRMPWR 27 LVD 26 L9+ 25 L9 - 24 L8+ 23 L8 - 22 L7+ 21 L7 -
L4+ 8 L4 - 9 DIFFB 10 DIFSENS 11 GND 12		17 L6+ 16 L6 - 15 L5+ 14 L5 - 13 DISCNCT	L4+ 9 L4 - 10 DIFFB 11 DIFSENS 12 N/C 13 GND 14		20 L6+ 19 L6 - 18 L5+ 17 L5 - 16 N/C 15 DISCNCT

### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

TERMPWR Voltage	6 V
Signal Line Voltage	
Package Dissipation	0.5 W
Storage Temperature	–65°C to 150°C
Junction Temperature	
Lead Temperature (Soldering, 10 sec.)	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

TERMPWR Voltage	2.7 V to 5.25 V
Operating Temperature Range	. 0°C to 70°C



# 9-LINE LVD-ONLY SCSI TERMINATOR WITH INTEGRATED SPI-3 DELAYS AND REVERSE DISCONNECT

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### electrical characteristics over recommended operating free-air temperature range, $T_A=T_J=0^\circ C$ to $70^\circ C,\, TRMPWR=2.7$ V to 5.25 V

Regulator output voltage $0.5 \text{ V} \le \text{V}_{\text{CM}} \le 2.0$ , See Note 1 1.15 1.25 1.35 V Regulator short-circuit source current VREG = 0 V -100 -80 mA Regulator short-circuit sink current VREG = 3.0 V 80 100 mA DIFSENS Output Section   Output voltage $-5 \text{ mA} \le \text{IDIFSENS} \le 50  \mu\text{A}$ 1.2 1.3 1.4 V Short-circuit source current VDIFSENS = 0 V -15 -5 mA Short-circuit sink current VDIFSENS = 2.75 V 50 200 $\mu\text{A}$ Differential Termination Section (Applies to each line pair , 1-9, in LVD mode)  Differential bias voltage L+ and L- shorted together, See Note 2 110 150 165 $\Omega$ Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)  Output leakage L+ and L- shorted together See Note 2 1.15 1.25 1.35 V Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)  Output capacitance Single-ended measurement to ground, See Note 3 pF	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Disabled Mode   Disabled M	TRMPWR Supply Current Section	•				
Regulator Section   Regulator output voltage   0.5 V ≤ V <sub>CM</sub> ≤ 2.0, See Note 1   1.15   1.25   1.35   V   Regulator short-circuit source current   V <sub>REG</sub> = 0.V   80   100   -80   mA   Regulator short-circuit sink current   V <sub>REG</sub> = 3.0 V   80   100   -80   mA   Regulator short-circuit sink current   V <sub>REG</sub> = 3.0 V   80   100   -80   mA   Regulator short-circuit sink current   V <sub>REG</sub> = 3.0 V   -15   -5   mA   Short-circuit source current   V <sub>DIFSENS</sub> = 50 µA   1.2   1.3   1.4   V   V   Short-circuit source current   V <sub>DIFSENS</sub> = 0.V   -15   -5   mA   Short-circuit source current   V <sub>DIFSENS</sub> = 2.75 V   50   200   µA   Differential Termination Section (Applies to each line pair, 1-9, in LVD mode)   Differential impedance   L+ and L- shorted together, See Note 2   110   150   165   Ω   Differential bias voltage   100   125   mV   Common-mode bias voltage   L+ and L- shorted together   1.15   1.25   1.35   V   Disconnected Termination Section (Applies to each line pair, 1-9, in DISCNCT, SE or HVD mode)   Uput Leakage   400   nA   Single-ended measurement to ground, See Note 3   pF   DISCNCT threshold   0.8   2.0   V   DISCNCT threshold   0.8   2.0   V   DISCNCT threshold   0.5   0.7   V   DIFFE SE to LVD threshold   0.5   0.7   V   DIFFE SE to LVD threshold   0.5   0.7   V   DIFFE SE to LVD threshold   0.5   0.7   V   DIFFE Input current   0.0 ≤ V <sub>DIFFE</sub> ≤ 2.75 V   -10   -10   10   µA   Low Voltage Differential (LVD) Status Bit Section (See Note 4)   -9   -6   -4   mA   Low Voltage Differential (LVD) Status Bit Section (See Note 4)   -9   -9   -9   -9   -9   -9   -9   -		LVD Mode (No Load)			35	mA
Regulator output voltage $0.5 \text{ V} \le \text{V}_{CM} \le 2.0$ , See Note 1 1.15 1.25 1.35 V Regulator short-circuit source current VREG = 0 V	TRMPWR supply current	Disabled Mode			500	μА
Regulator short-circuit source current $V_{REG} = 0 \text{ V}$ 100 *80 mA Regulator short-circuit sink current $V_{REG} = 3.0 \text{ V}$ 80 100 mA DIFSENS Output Section  Output voltage 5 mA $\leq$ IDIFSENS $\leq$ 50 $\neq$ MA 1.2 1.3 1.4 V Nont-circuit source current VDIFSENS $\leq$ 50 $\neq$ MA 1.2 1.3 1.4 V Short-circuit source current VDIFSENS $\leq$ 50 $\neq$ MA 1.5 5 mA Short-circuit sink current VDIFSENS $\leq$ 2.75 $\vee$ 50 200 $\neq$ MA Differential Termination Section (Applies to each line pair , 1-9, in LVD mode)  Differential impedance 100 105 110 150 165	Regulator Section	•				
Regulator short-circuit sink current   V_REG = 3.0 V   80   100   mA	Regulator output voltage	$0.5 \text{ V} \le \text{V}_{CM} \le 2.0$ , See Note 1	1.15	1.25	1.35	V
DIFSENS Output Section           Output voltage         −5 mA ≤ I <sub>DIFSENS</sub> ≤ 50 μA         1.2         1.3         1.4         V           Short-circuit source current         V <sub>DIFSENS</sub> = 0 V         -15         -5         mA           Short-circuit sinc current         V <sub>DIFSENS</sub> = 2.75 V         50         200         μA           Differential Termination Section (Applies to each line pair , 1-9, in LVD mode)         Differential impedance         100         105         110         Ω           Common-mode impedance         L+ and L- shorted together, See Note 2         110         150         165         Ω           Differential bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           Output capacitance         Single-ended measurement to ground, See Note 3         pF           DISCNCT and DIFFB Input Section         3         pF           DISCNCT threshold         0.8         2.0         V           DIFFB SE to LVD threshold <t< td=""><td>Regulator short-circuit source current</td><td>V<sub>REG</sub> = 0 V</td><td></td><td>-100</td><td>-80</td><td>mA</td></t<>	Regulator short-circuit source current	V <sub>REG</sub> = 0 V		-100	-80	mA
Output voltage	Regulator short-circuit sink current	V <sub>REG</sub> = 3.0 V	80	100		mA
Short-circuit source current   V_DIFSENS = 0 V   -15   -5   mA	DIFSENS Output Section	•				
Short-circuit sink current         V <sub>DIFSENS</sub> = 2.75 V         50         μA           Differential Termination Section (Applies to each line pair , 1-9, in LVD mode)         UPDIFFER INDIFFER INDIFFER SETION (Applies to each line pair , 1-9, in LVD mode)           Differential impedance         L+ and L- shorted together, See Note 2         110         150         165         Ω           Differential bias voltage         L+ and L- shorted together         1.05         1.25         mV           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         vV           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         Single-ended measurement to ground, See Note 3         400         nA           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         √DISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB LVD to HVD threshold         0.5         0.7         V           DIFFB Input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)           Isource         VLOAD = 2.4 V	Output voltage	−5 mA ≤ IDIFSENS ≤ 50 μA	1.2	1.3	1.4	V
Differential Termination Section (Applies to each line pair , 1-9, in LVD mode)           Differential impedance         100         105         110         Ω           Common-mode impedance         L+ and L- shorted together, See Note 2         110         150         165         Ω           Differential bias voltage         100         125         mV           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           Output capacitance         Single-ended measurement to ground, See Note 3         a         pF           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         VDISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB Input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         -6         -4         mA           Ison K         VLOAD = 2.4 V <td< td=""><td>Short-circuit source current</td><td>V<sub>DIFSENS</sub> = 0 V</td><td>-15</td><td></td><td>-5</td><td>mA</td></td<>	Short-circuit source current	V <sub>DIFSENS</sub> = 0 V	-15		-5	mA
Differential impedance         100         105         110         Ω           Common-mode impedance         L+ and L- shorted together, See Note 2         110         150         165         Ω           Differential bias voltage         L+ and L- shorted together         1.00         125         mV           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           Output capacitance         Single-ended measurement to ground, See Note 3         3         pF           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         VDISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVD threshold         0.9         0.5         0.7         V           DIFFB Input current         0.0 ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         2         5         mA	Short-circuit sink current	V <sub>DIFSENS</sub> = 2.75 V	50		200	μА
Common-mode impedance         L+ and L- shorted together, See Note 2         110         150         165         Ω           Differential bias voltage         L+ and L- shorted together         1.00         125         mV           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         Voisconct = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVVD threshold         1.9         2.4         V           DIFFB Input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Lew Voltage Differential (LVD) Status Bit Section (See Note 4)         2         5         mA           ISOURCE         VLOAD = 2.4 V         2         5         mA           ISINK         VLOAD = 0.4 V         2         5         mA           Time Delay/Filter Sectio	Differential Termination Section (Applies to	each line pair , 1-9, in LVD mode)				
Differential bias voltage         L+ and L- shorted together         1.00         125         mV           Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           Output capacitance         Single-ended measurement to ground, See Note 3         3         pF           DISCNCT and DIFFB Input Section         0.8         2.0         V           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         √DISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVD threshold         1.9         2.4         V           DIFFB input current         0 V ≤ V <sub>DIFFB</sub> ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         2         5         mA           I'SOURCE         V <sub>LOAD</sub> = 2.4 V         2         5         mA           I'SINK         V <sub>LOAD</sub> = 0.4 V         2         5         mA           Time Delay/Filter Section	Differential impedance		100	105	110	Ω
Common-mode bias voltage         L+ and L- shorted together         1.15         1.25         1.35         V           Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)           Output leakage         400         nA           Output capacitance         Single-ended measurement to ground, See Note 3         3         pF           DISCNCT and DIFFB Input Section         0.8         2.0         V           DISCNCT input current         √DISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVD threshold         1.9         2.4         V           DIFFB input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         VLOAD = 2.4 V         -6         -4         mA           ISINK         VLOAD = 0.4 V         2         5         mA           Time Delay/Filter Section           Mode change delay         A new mode change can start any time after a previous mode change has been detected         100         190         300         ms           Thermal Shutdown Section         For increasing temperature         140         155	Common-mode impedance	L+ and L- shorted together, See Note 2	110	150	165	Ω
Disconnected Termination Section (Applies to each line pair , 1-9, in DISCNCT, SE or HVD mode)         400 nA           Output leakage         Single-ended measurement to ground, See Note 3         3 pF           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8 2.0 V           DISCNCT input current         VDISCNCT = 0 V and 2.0 V         -30 -10 µA           DIFFB SE to LVD threshold         0.5 0.7 V           DIFFB LVD to HVD threshold         1.9 2.4 V           DIFFB input current         0 V ≤ VDIFFB ≤ 2.75 V         -10 10 µA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         VLOAD = 2.4 V         -6 -4 mA           ISINK         VLOAD = 2.4 V         2 5 mA           Time Delay/Filter Section         A new mode change can start any time after a previous mode change has been detected         100 190 300 ms           Thermal Shutdown Section         For increasing temperature         140 155 170 °C	Differential bias voltage		100		125	mV
Output leakage         Single-ended measurement to ground, See Note 3         400         nA           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         VDISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVD threshold         1.9         2.4         V           DIFFB input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         UCAD = 2.4 V         -6         -4         mA           ISINK         VLOAD = 0.4 V         2         5         mA           Time Delay/Filter Section           Mode change delay         A new mode change can start any time after a previous mode change has been detected         100         190         300         ms           Thermal Shutdown Section           Themal shutdown threshold         For increasing temperature         140         155         170         °C	Common-mode bias voltage	L+ and L- shorted together	1.15	1.25	1.35	V
Output capacitance         Single-ended measurement to ground, See Note 3         pF           DISCNCT and DIFFB Input Section           DISCNCT threshold         0.8         2.0         V           DISCNCT input current         VDISCNCT = 0 V and 2.0 V         -30         -10         μA           DIFFB SE to LVD threshold         0.5         0.7         V           DIFFB LVD to HVD threshold         1.9         2.4         V           DIFFB input current         0 V ≤ VDIFFB ≤ 2.75 V         -10         10         μA           Low Voltage Differential (LVD) Status Bit Section (See Note 4)         VLOAD = 2.4 V         -6         -4         mA           ISUNK         VLOAD = 2.4 V         2         5         mA           Time Delay/Filter Section         A new mode change can start any time after a previous mode change has been detected         100         190         300         ms           Thermal Shutdown Section           Themal shutdown threshold         For increasing temperature         140         155         170         °C	Disconnected Termination Section (Applies	to each line pair , 1-9, in DISCNCT, SE or HVD mode)				
DISCNCT and DIFFB Input Section   DISCNCT threshold   DISCNCT threshold   DISCNCT input current   VDISCNCT = 0 V and 2.0 V   -30   -10   μA	Output leakage				400	nA
DISCNCT threshold0.82.0VDISCNCT input current $V_{DISCNCT} = 0 \text{ V}$ and 2.0 V-30-10μADIFFB SE to LVD threshold0.50.7VDIFFB LVD to HVD threshold1.92.4VDIFFB input current $0 \text{ V} \leq \text{VDIFFB} \leq 2.75 \text{ V}$ -1010μALow Voltage Differential (LVD) Status Bit Section (See Note 4)ISOURCE $V_{LOAD} = 2.4 \text{ V}$ -6-4mAISINK $V_{LOAD} = 0.4 \text{ V}$ 25mATime Delay/Filter SectionMode change delayA new mode change can start any time after a previous mode change has been detected100190300msThermal Shutdown SectionThemal shutdown thresholdFor increasing temperature140155170°C	Output capacitance				3	pF
DISCNCT input current $\sqrt{\text{DISCNCT}} = 0 \text{ V}$ and $2.0 \text{ V}$ -30-10μADIFFB SE to LVD threshold0.50.7VDIFFB LVD to HVD threshold1.92.4VDIFFB input current $0 \text{ V} \le \text{VDIFFB} \le 2.75 \text{ V}$ -1010μALow Voltage Differential (LVD) Status Bit Section (See Note 4) $ SOURCE $ $V_{LOAD} = 2.4 \text{ V}$ -6-4mA $ SINK $ $V_{LOAD} = 0.4 \text{ V}$ 25mATime Delay/Filter SectionMode change delayA new mode change can start any time after a previous mode change has been detected100190300msThermal Shutdown SectionThemal shutdown thresholdFor increasing temperature140155170°C	DISCNCT and DIFFB Input Section	·				
DIFFB SE to LVD threshold 0.5 0.7 V  DIFFB LVD to HVD threshold 1.9 2.4 V  DIFFB input current 0 V $\leq$ V DIFFB $\leq$ 2.75 V -10 10 $\downarrow$ $\downarrow$ A  Low Voltage Differential (LVD) Status Bit Section (See Note 4)   SOURCE   V_LOAD = 2.4 V -6 -4   mA   SINK   V_LOAD = 0.4 V   2   5   mA  Time Delay/Filter Section  Mode change delay   A new mode change can start any time after a previous mode change has been detected 100 190 300 ms  Thermal Shutdown Section  Themal shutdown threshold   For increasing temperature 140 155 170 °C	DISCNCT threshold		0.8		2.0	V
DIFFB LVD to HVD threshold 1.9 2.4 V DIFFB input current 0 V $\leq$ VDIFFB $\leq$ 2.75 V -10 10 $\mu$ A  Low Voltage Differential (LVD) Status Bit Section (See Note 4)  ISOURCE VLOAD = 2.4 V -6 -4 $\mu$ A  ISINK VLOAD = 0.4 V 2 5 $\mu$ A  Time Delay/Filter Section  Mode change delay A new mode change can start any time after a previous mode change has been detected 100 190 300 $\mu$ S  Thermal Shutdown Section  Themal shutdown threshold For increasing temperature 140 155 170 °C	DISCNCT input current	VDISCNCT = 0 V and 2.0 V	-30	-10		μΑ
DIFFB input current $0 \ V \le V_{DIFFB} \le 2.75 \ V$ -10 10 $\mu A$ Low Voltage Differential (LVD) Status Bit Section (See Note 4)  ISOURCE $V_{LOAD} = 2.4 \ V$ -6 -4 $\mu A$ ISINK $V_{LOAD} = 0.4 \ V$ 2 5 $\mu A$ Time Delay/Filter Section  Mode change delay $A_{LOAD} = 0.4 \ V$ 100 190 300 $\mu A$ Thermal Shutdown Section  Thermal Shutdown threshold For increasing temperature 140 155 170 °C	DIFFB SE to LVD threshold		0.5		0.7	V
Low Voltage Differential (LVD) Status Bit Section (See Note 4)   SOURCE	DIFFB LVD to HVD threshold		1.9		2.4	V
SOURCE   VLOAD = 2.4 V   -6   -4   mA     SINK   VLOAD = 0.4 V   2   5   mA     Time Delay/Filter Section   A new mode change can start any time after a previous mode change has been detected   100   190   300   ms     Thermal Shutdown Section   Themal shutdown threshold   For increasing temperature   140   155   170   °C	DIFFB input current	0 V ≤ V <sub>DIFFB</sub> ≤ 2.75 V	-10		10	μΑ
ISINK     VLOAD = 0.4 V     2     5     mA       Time Delay/Filter Section       Mode change delay     A new mode change can start any time after a previous mode change has been detected     100     190     300     ms       Thermal Shutdown Section       Themal shutdown threshold     For increasing temperature     140     155     170     °C	Low Voltage Differential (LVD) Status Bit Se	ection (See Note 4)				
Time Delay/Filter Section  Mode change delay  A new mode change can start any time after a previous mode change has been detected  Thermal Shutdown Section  Themal shutdown threshold  For increasing temperature  100 190 300 ms  100 190 300 ms	ISOURCE	V <sub>LOAD</sub> = 2.4 V		-6	-4	mA
Mode change delay  A new mode change can start any time after a previous mode change has been detected  100 190 300 ms  Thermal Shutdown Section  Themal shutdown threshold  For increasing temperature  140 155 170 °C	ISINK	$V_{LOAD} = 0.4 V$	2	5		mA
Thermal Shutdown Section  Themal shutdown threshold  For increasing temperature  100  190  300  IIIS  100  190  300  IIIS	Time Delay/Filter Section					
Themal shutdown threshold For increasing temperature 140 155 170 °C	Mode change delay		100	190	300	ms
3 1	Thermal Shutdown Section					
Themal shutdown hysteresis 10 °C	Themal shutdown threshold	For increasing temperature	140	155	170	°C
	Themal shutdown hysteresis			10		°C

NOTES: 1. V<sub>CM</sub> is applied to all L+ and L- lines simultaneously.

2. 
$$Z_{CM} = \frac{(2.0V - 0.5V)}{\left[I_{VCM(max)} - I_{VCM(min)}\right]} @ VCM(max) = 2.0, VCM(min) = 0.5 V$$

- 3. Ensured by design, not production tested.
- 4. This applies to the 28-pin package only.



## UCC5681 9-LINE LVD-ONLY SCSI TERMINATOR WITH INTEGRATED SPI-3 DELAYS AND REVERSE DISCONNECT

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### pin descriptions

**DIFFB:** DIFFSENS input pin. Connect through a 20-k $\Omega$  resistor to DIFSENS and through a 0.1- $\mu$ F capacitor to ground. Input to comparators that detect what types of drivers are connected to the SCSI bus.

**DIFSENS:** SCSI bus DIFSENS line driver.

**DISCNCT:** Disconnect pin. Shuts down the terminator (switches terminating resistors off the bus) when tied to GND. The disconnect pin high (or OPEN) enables the terminator.

GND: Power supply return.

LINEn:: Line termination pins. Negative line in differential pair.

**LINE***n***+:** Line termination pins. Positive line in differential pair.

LVD: (28-pin package only) Indicates that the bus is in LVD mode.

**REG:** Regulator bypass pin. Bypass near the terminator with a  $4.7-\mu F$  and a high-frequency, low-ESR  $0.01-\mu F$  capacitor to ground.

**TRMPWR:**  $V_{IN}$  2.75 V to 5.25 V supply. Bypass near the terminator with a 4.7- $\mu$ F and a high-frequency, low-ESR 0.01- $\mu$ F capacitor to ground.

#### **APPLICATION INFORMATION**

All SCSI buses require a termination network at each end to function properly. Specific termination requirements differ, depending on which types of SCSI driver devices are present on the bus. The UCC5681 is a low-voltage differential (LVD)-only device. It senses which types of drivers are present on the bus. If it detects the presence of a single-ended (SE) or high-voltage differential (HVD) driver, the UCC5681 will place itself in a high-impedance input state, effectively disconnecting the chip from the bus.

The UCC5681 senses what kinds of drivers are present on the bus by the voltage on SCSI bus control line DIFFSENS, which is monitored by the DIFFB input pin. The DIFSENS output pin on the UCC5681 attempts to drive a DIFFSENS control line to 1.3 V. If only LVD devices are present, the DIFFSENS line will be successfully driven to that voltage. If HVD drivers are present, they will pull the DIFFSENS line high. If any single-ended drivers are present, they pull the DIFSENS line to ground (even if HVD drivers are also present on the bus). If the voltage on the DIFFB is below 0.5 V or above 2.4 V, the UCC5681 enters the high-impedance SE/HVD state. If it is between 0.7 V and 1.9 V, the UCC5681 enters the LVD mode. These thresholds accommodate differences in ground potential that can occur between the ends of long bus lines.

Three UCC5681 ICs are required at each end of the SCSI bus to terminate 27 lines (18 data, 9 control). Every UCC5681 contains a DIFSENS driver, but only one should be used to drive the line at each end. The DIFSENS pin on the other devices should be left unconnected.

On power up (the voltage on the TRMPWR pin rising above 2.7 V), the UCC5681 assumes the SE/HVD mode. If the voltage on the DIFFB input indicates LVD mode, the chip waits 100 ms to 300 ms before changing the mode of the bus. If the voltage at the DIFFB input later crosses one of the thresholds, the UCC5681 again waits 100 ms to 300 ms before changing the mode of the bus. The magnitude of the delay is the same when changing in or out of either bus mode. A new mode change can start anytime after a previous mode change has been detected.

The DIFFB inputs on all three chips at each end of the bus should be connected together. Properly filtered, noise on DIFFB will not cause a false mode change. There should be a shared 50-Hz noise filter implemented on DIFFB at each end of the bus as close as possible to the DIFFB pins. This is implemented with a  $20-k\Omega$  resistor between the DIFFB and DIFSENS pins, and a  $0.1-\mu$ F capacitor from DIFFB to ground. See the *Typical Application* diagram at the end of this datasheet.



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### **APPLICATION INFORMATION (continued)**

In LVD mode, the regulated voltage is switched to 1.25 V and a resistor network is presented to each line pair that provides common-mode impedance of 150  $\Omega$  and differential impedance of 105  $\Omega$ . The lines in each differential pair are biased so that when not driven, Line(n)+ and Line(n)- are driven 56 mV below and above the common-mode bias voltage (1.25 V) respectively.

In SE/HVD mode, all the terminating resistors are switched off the bus. The 1.25-V and 1.3-V (DIFSENS) regulators are left on.

When the disconnect input (DISCNCT) is low, the terminating resistors are switched off the bus and both voltage regulators are turned off to save power. The mode change filter/delay function is still active and the LVD pin (in the 28-pin package) continues to indicate the correct bus mode.

The UCC5681 operates down to a TRMPWR voltage of 2.7 V. This accommodates a 3.3-V system with allowance for supply tolerance ( $\pm 10\%$ ), a unidirectional fusing device, and cable drop. The UCC3916 is recommended in place of a fuse and diode implementation, as its lower voltage drop provides additional voltage margin for the system.

Layout is important in all SCSI implementations and critical in SPI-3 systems, which have stringent requirements on both the absolute value of capacitance on differential signal lines and the balancing of capacitance between paired lines and from pair to pair.

Feedthroughs, through-hole connections, and etch lengths need to be carefully balanced. Standard multilayer power and ground plane spacing adds about 1 pF to each plane. Each feed-through will add 2.5 pF to 3.5 pF. Enlarging the clearance holes on both power and ground planes reduces capacitance. Opening up the power and ground planes under a through-hole connector reduces added capacitance in those applications. Capacitance is also affected by components in close proximity on both sides of the board.

#### maximum capacitance

SCSI Class	Trace to GND: REQ, ACK, DATA, Parity, P_CRCA	Trace to Trace: REQ, ACK, DATA, Parity, P_CRCA	Trace to GND: Other signals	Trace to Trace: Other Signals
Ultra1	25 pF	N/A	25 pF	N/A
Ultra2	20 pF	10 pF	25 pF	13 pF
Ultra3/Ultra160	15 pF	8 pF	25 pF	13 pF
Ultra320	13 pF	6.5 pF	21 pF (est.)	10 pF (est.)

TI terminators are designed with very tightly controlled capacitance on their signal lines. Between the positive and negative lines in a differential pair the difference is typically no more than 0.1 pF, and only 0.3 pF between pairs.

Multi-layer boards need to adhere to the  $120-\Omega$  impedance standard, including the connector and feedthroughs. Bus traces are normally run on the outer layers of the board with 4-mil etch and 4-mil spacing between the two lines in each differential pair, and a minimum of 8-mil spacing to adjacent pairs to minimize crosstalk. Microstrip technology is too low in impedance and should not be used—it is designed for  $50~\Omega$  rather than  $120-\Omega$  differential systems.

Decoupling capacitors should be installed as close as possible to the following input pins of the UCC5681:

TRMPWR: 4.7-μF capacitor to ground, 0.01-μF capacitor to ground (high-frequency, low ESR)

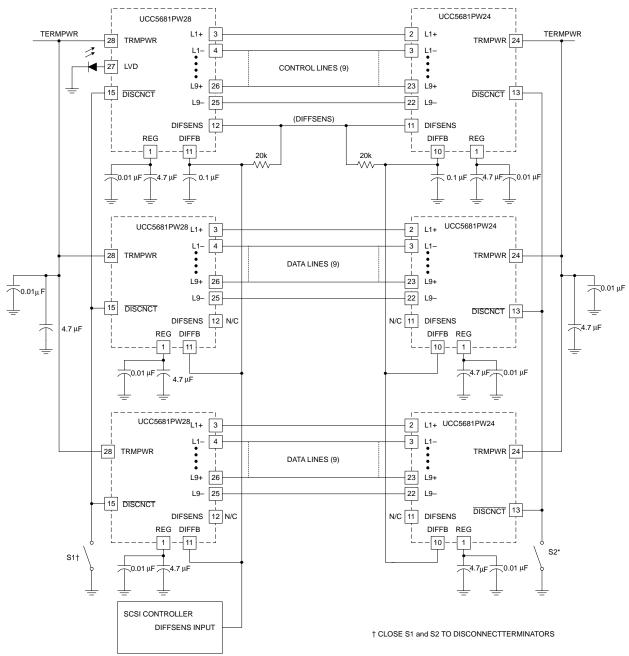
REG: 4.7-μF capacitor to ground, 0.01-μF capacitor to ground (high-frequency, low ESR)



### 9-LINE LVD-ONLY SCSI TERMINATOR WITH INTEGRATED SPI-3 DELAYS AND REVERSE DISCONNECT

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### **TYPICAL APPLICATION**



UDG-00125



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